

## 800V N-Channel MOSFET

### Description

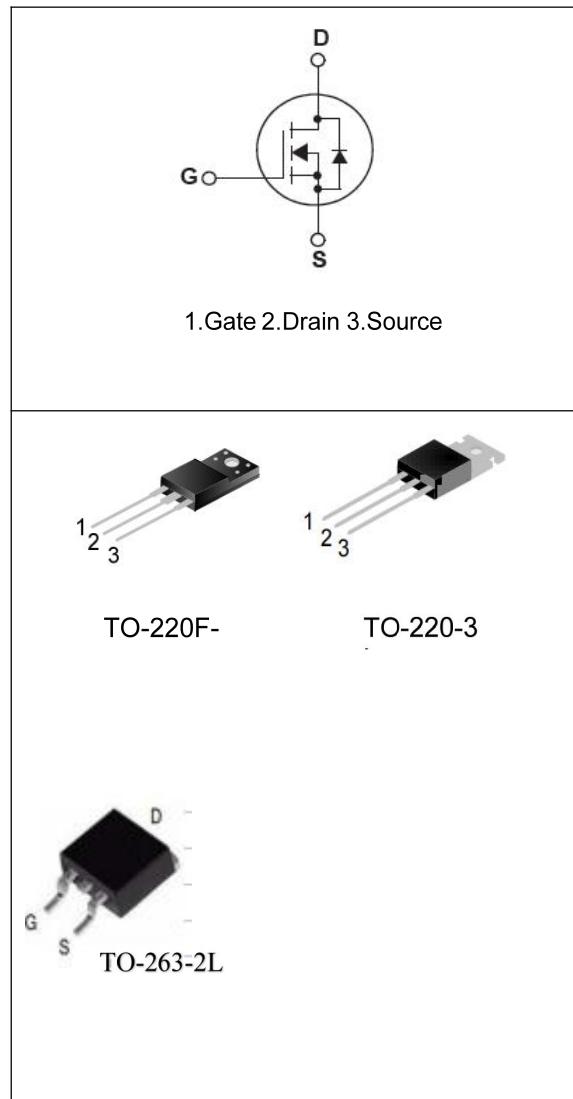
SR80R240 is new generation of high voltage MOSFET family that is utilizing an advanced charge balance mechanism for outstanding low on-resistance and lower gate charge performance.

This advanced technology has been tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate and higher avalanche energy.

SJ-FET is suitable for various AC/DC power conversion in switching mode operation for higher efficiency..

### Features

- Multi-Epi process SJ-FET
- 850V @TJ = 150 °C
- Typ. RDS(on) = 0.22Ω
- Ultra Low Gate Charge (typ. Qg = 27.5nC)
- 100% avalanche tested



### Package Marking and Ordering Information:

Marking	Package	Part #	Hazardous Substance Control	Packing
SR80R240F	T0-220F-3L	SR80R240F	Pb free	Tube
SR80R240T	T0-220-3L	SR80R240T	Pb free	Tube
SR80R240S	TO-263-2L	SR80R240S	Pb free	Tube

**Absolute Maximum Ratings**

Symbol	Parameter	SR80R240T/S	SR80R240F	Unit
VDSS	Drain-Source Voltage	800		V
ID	Drain Current -Continuous (TC = 25°C)	18.4*		
	-Continuous (TC = 100°C)	11.6*		A
IDM	Drain Current – Pulsed (Note 1)	51*		A
VGSS	Gate-Source voltage	±30		V
EAS	Single Pulsed Avalanche Energy (Note 2)	485		mJ
IAR	Avalanche Current (Note 1)	3.5		A
dv/dt	Peak Diode Recovery dv/dt (Note 3)	15		V/ns
dVds/dt	Drain Source voltage slope (Vds=640V)	50		V/ns
PD	Power Dissipation (TC = 25°C)	151	35	W
TJ, TSTG	Operating and Storage Temperature Range	-55 to +150		°C
TL	Maximum Lead Temperature for Soldering			
	Purpose, 1/8" from Case for 5 Seconds	300		°C

\* Drain current limited by maximum junction temperature . Maximum duty cycle D=0.75.

**Thermal Characteristics**

Symbol	Parameter	SR80R240T/S	SR80R240F	Unit
R <sub>θJC</sub>	Thermal Resistance, Junction-to-Case	0.83	3.7	°C/W
R <sub>θCS</sub>	Thermal Resistance, Case-to-Sink Typ.	0.5	-	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient	62	80	°C/W

**Electrical Characteristics TC = 25°C unless otherwise noted**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA, T <sub>J</sub> = 25 °C	800	-	-	V
		V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA, T <sub>J</sub> = 150 °C	-	850	-	V
ΔBV <sub>DSS</sub> / ΔT <sub>J</sub>	Breakdown Voltage Temperature Coefficient	I <sub>D</sub> = 250μA, Referenced to 25 °C	-	0.6	-	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 800V, V <sub>GS</sub> = 0V ·T <sub>J</sub> = 150 °C	-	- 10	1 -	μA μA
I <sub>GSSF</sub>	Gate-Body Leakage Current, Forward	V <sub>GS</sub> = 30V, V <sub>DS</sub> = 0V	-	-	100	nA
I <sub>GSSR</sub>	Gate-Body Leakage Current, Reverse	V <sub>GS</sub> = -30V, V <sub>DS</sub> = 0V	-	-	-100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	2.5	3.5	4.5	V
R <sub>DS(on)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> = 10V, I <sub>D</sub> = 9A	-	0.22	0.26	Ω
g <sub>FS</sub>	Forward Trans conductance	V <sub>DS</sub> = 40V, I <sub>D</sub> = 18A	-	19	-	S
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 25V, V <sub>GS</sub> = 0V, f = 1MHz	-	1290	-	pF
C <sub>oss</sub>	Output Capacitance		-	380	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	22	-	pF
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> = 400V, I <sub>D</sub> = 10A R <sub>G</sub> = 25Ω (Note 4)	-	40	-	ns
t <sub>r</sub>	Turn-On Rise Time		-	21	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		-	139	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	21	-	ns
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> = 450V, I <sub>D</sub> = 10A V <sub>GS</sub> = 10V (Note 4)	-	27.5	-	nC
Q <sub>gs</sub>	Gate-Source Charge		-	6.3	-	nC
Q <sub>gd</sub>	Gate-Drain Charge		-	11.2	-	nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain-Source Diode Forward Current		-	-	18	A
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current		-	-	51	A
V <sub>SD</sub>	Drain-Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>F</sub> = 20A	-	1	1.5	V

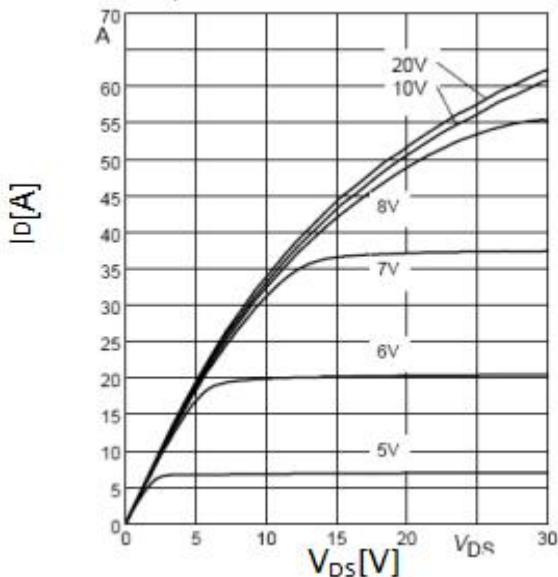
trr	Reverse Recovery Time	VR = 400V, VGS = 0V, IF = 20A, dI/dt = 100A/μs	-	710	-	ns
Qrr	Reverse Recovery Charge		-	13	-	μC
Irrm	Peak reverse recovery Current		-	33	-	A

**NOTES:**

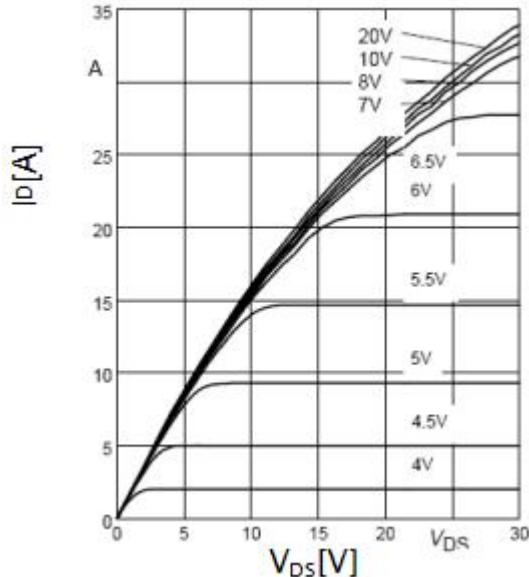
- 1.Repetitive Rating: Pulse width limited by maximum junction temperature
- 2.IAS=3.5A, VDD=50V, Starting TJ=25 °C
- 3.ISD≤ID, di/dt ≤ 200A/us, VDD ≤ BVDSS, Starting TJ = 25 °C
- 4.Essentially Independent of Operating Temperature Typical Characteristics

## Typical Performance Characteristics

Figuer1:On-Region Characteristics@25°C

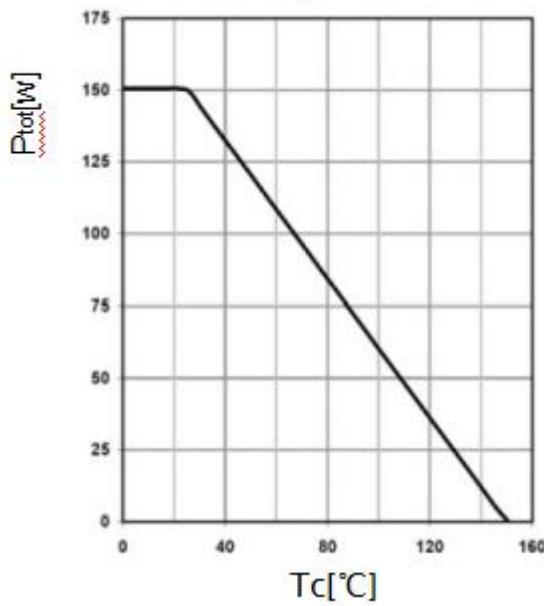


Figuer2:On-Region Characteristics@125°C



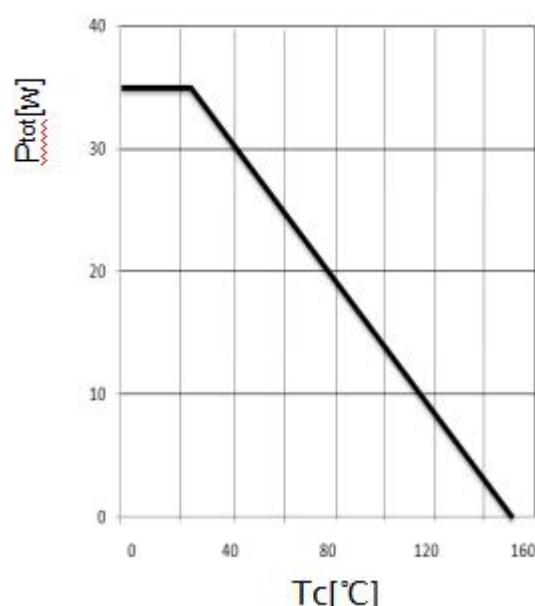
Figuer3:Power Dissipation

TO-220/263



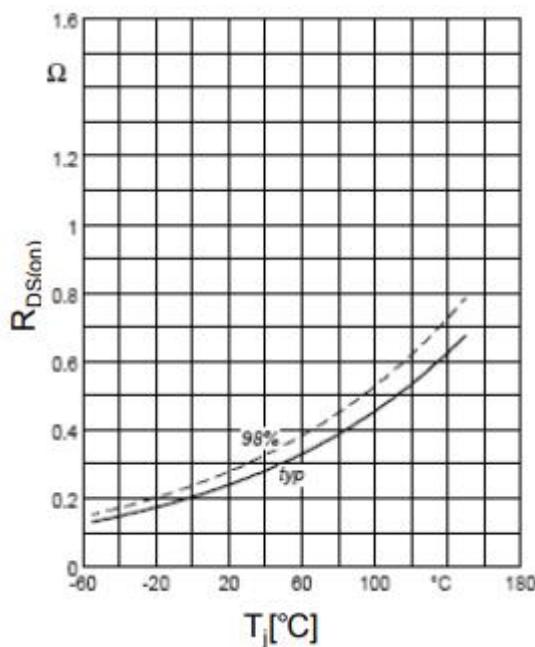
Figuer4:Power Dissipation

TO-220FullPAK

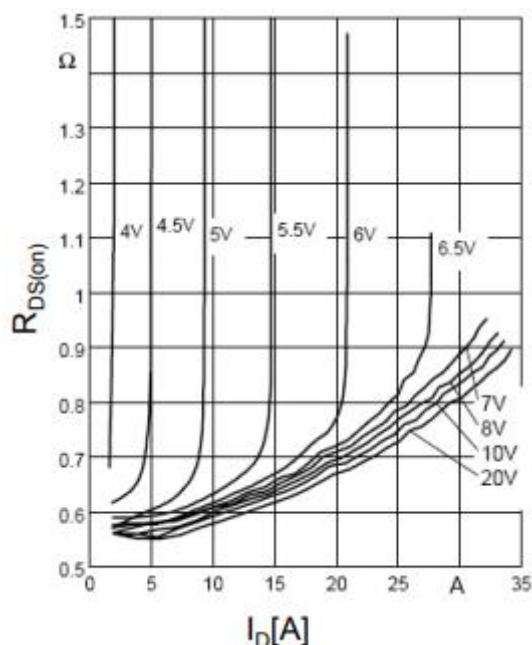


## Typical Performance Characteristics

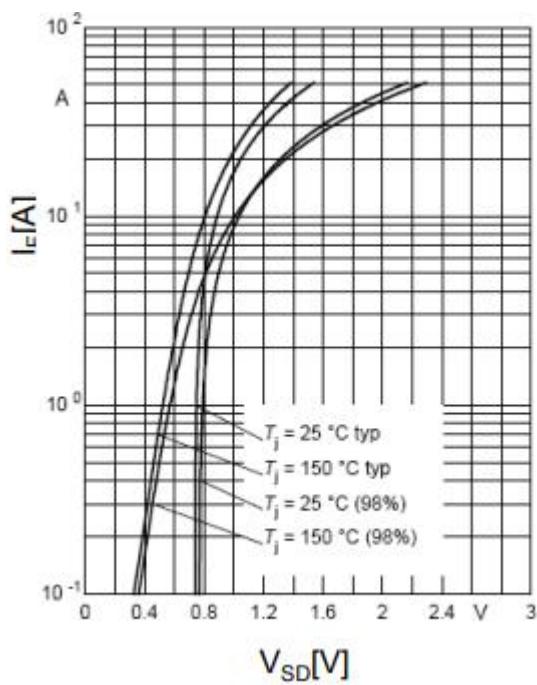
Figuer5:On-Resistance vs.  
Junction Temperature



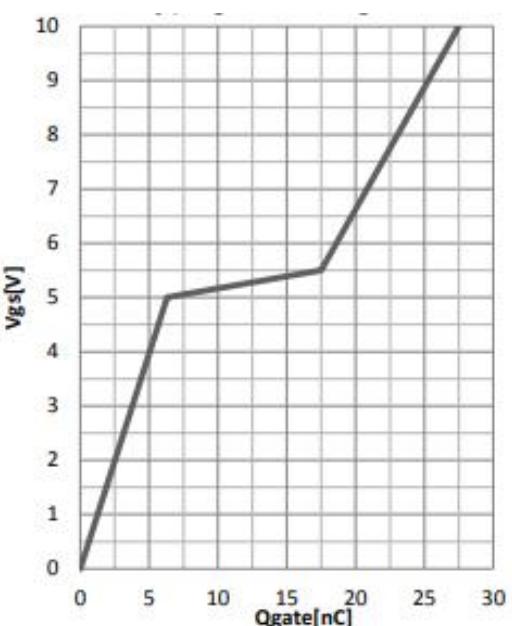
Figuer6:On-Resistance vs.  
Drain Current,  $T_j=125^\circ\text{C}$



Figuer7:Body-Diode Characteristics

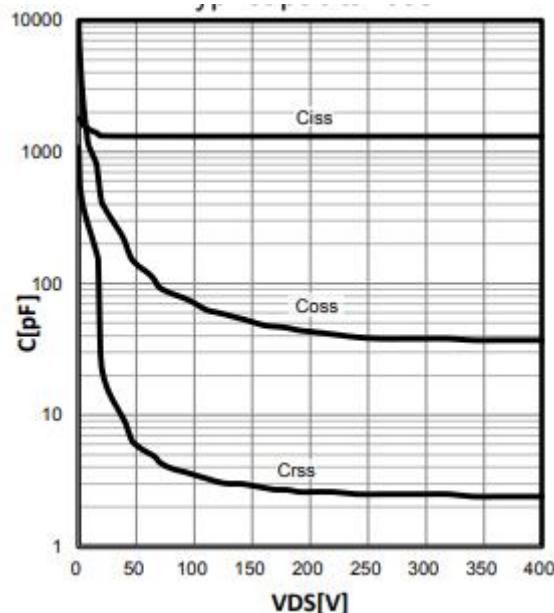


Figuer8:Gate-Charge Characteristics



## Typical Performance Characteristics

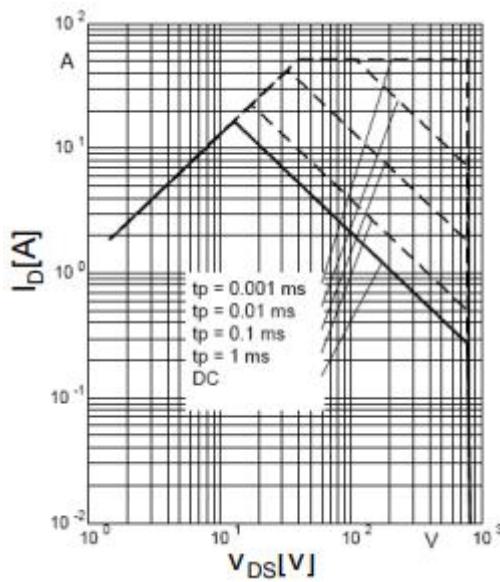
Figuer9:Capacitance Characteristics



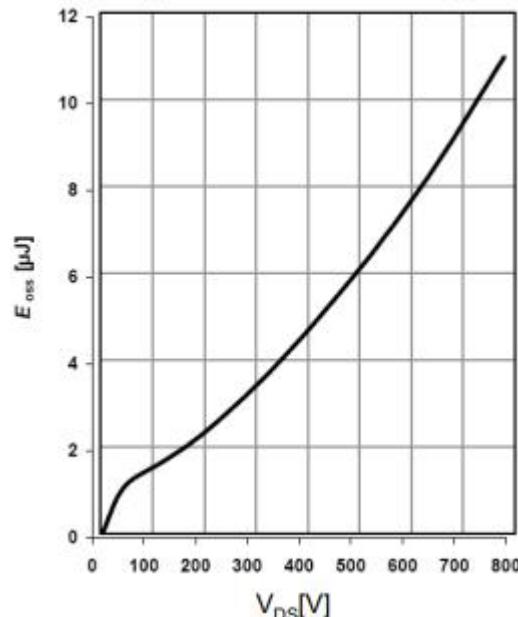
Figuer11:Maximum Forward Biased

Safe Operating Area

$T_c=25^\circ\text{C}$ , TO-220,TO-263



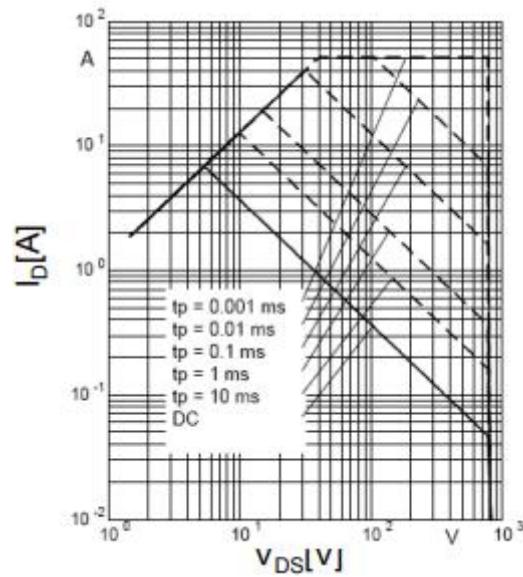
Figuer10:Coss stored Energy



Figuer12:Maximum Forward Biased

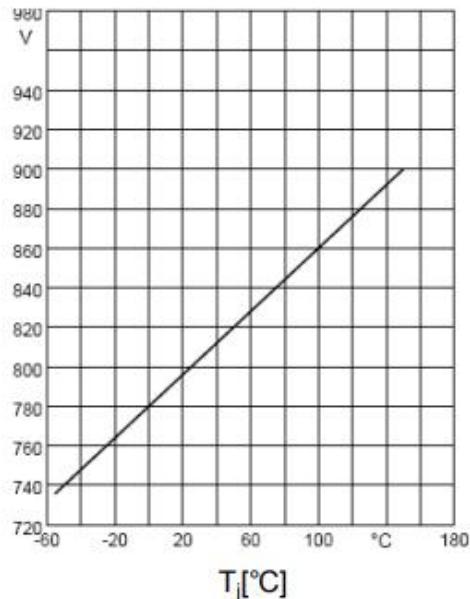
Safe Operating Area

$T_c=25^\circ\text{C}$ , TO-220 FullPAK

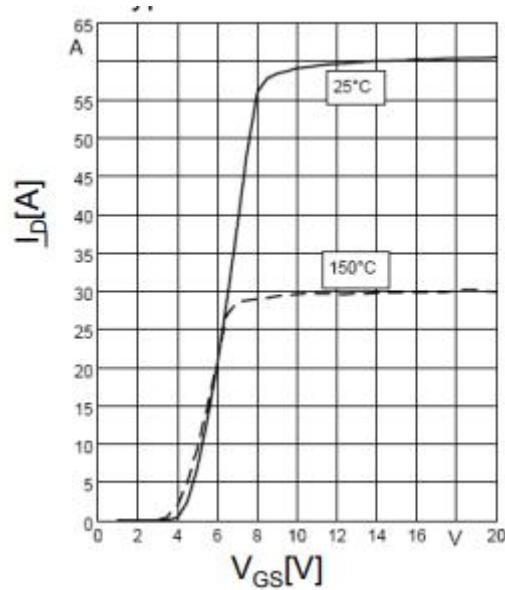


## Typical Performance Characteristics

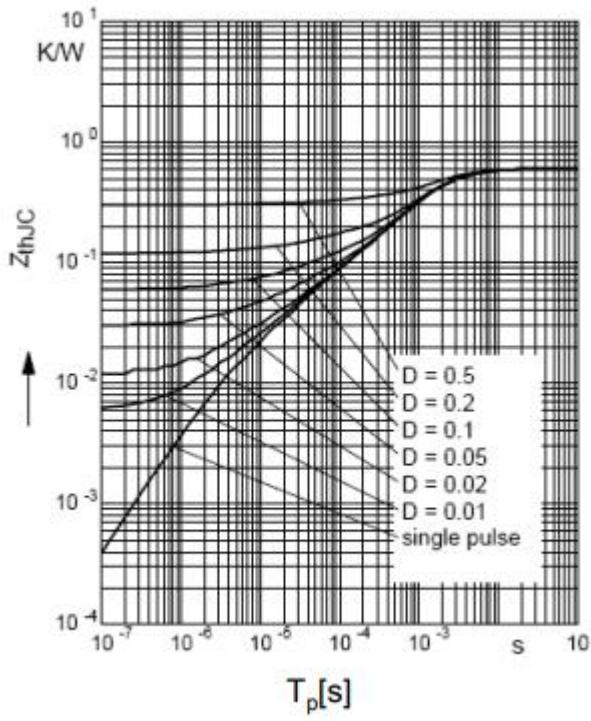
Figuer13:Break Down vs.  
Junction Temperature



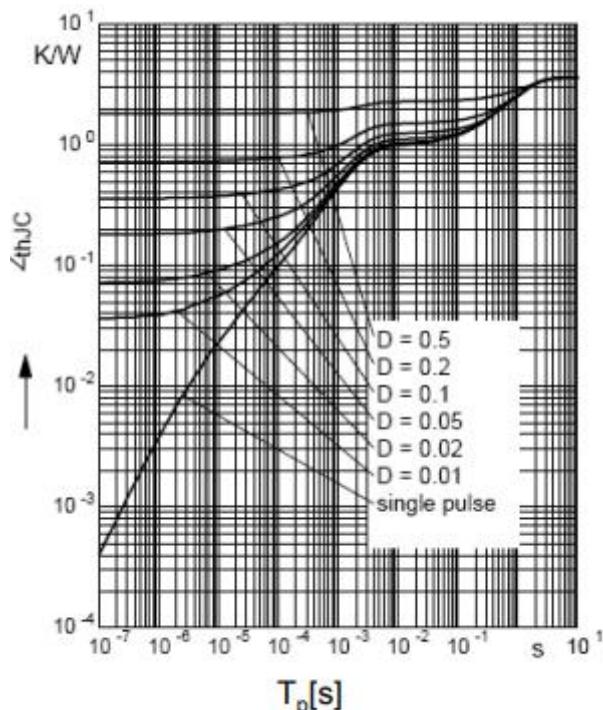
Figuer14:Typical transfer  
charactnristics



Figuer15:Maximum Transient Thermal Impedance TO-220,TO-263

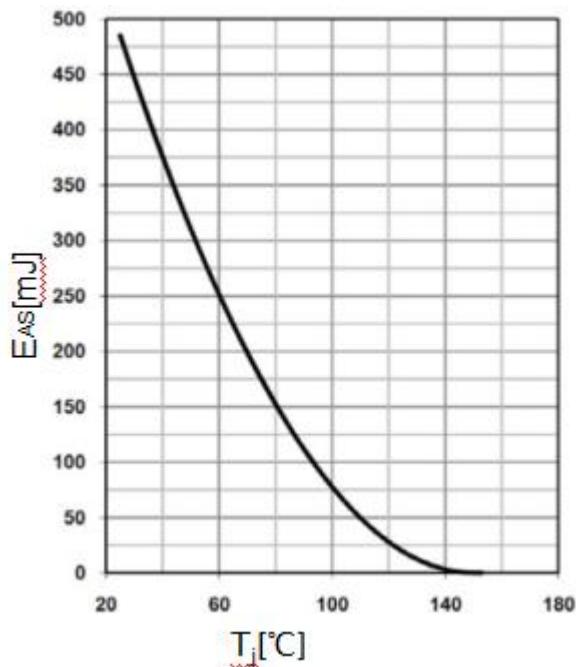


Figuer16:Maximum Transient Thermal Impedance TO-220 FullPAK



## Typical Performance Characteristics

Figure17:Avalanche energy

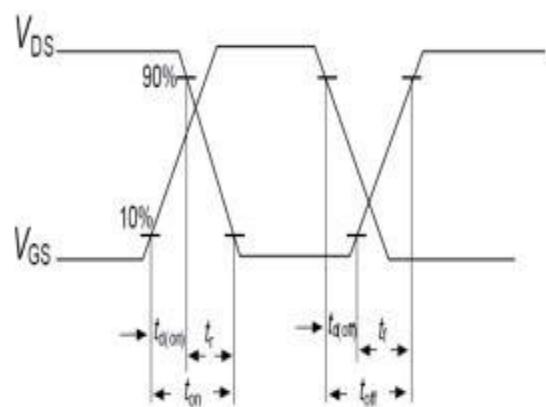
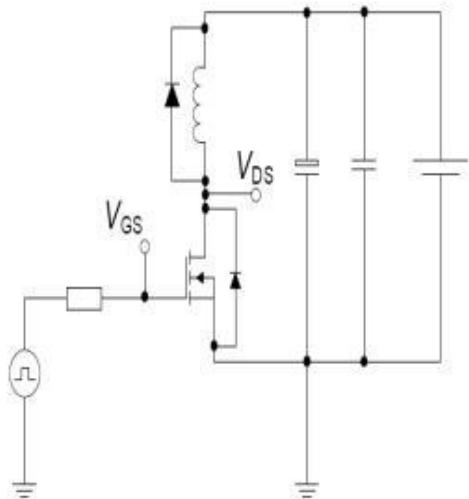


### Test circuits

Switching times test circuit and waveform for inductive load

Switching times test circuit for inductive load

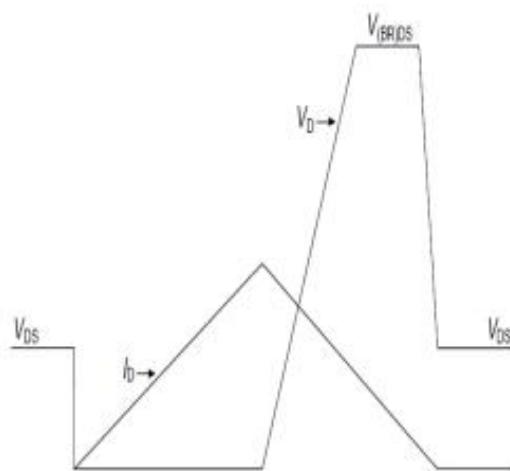
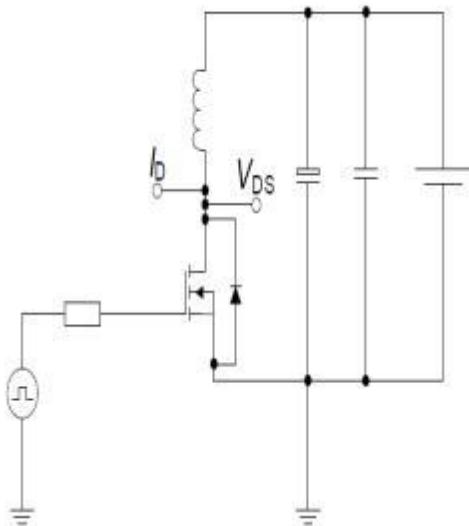
Switching time waveform



Unclamped inductive load test circuit waveform

Unclamped inductive load test circuit

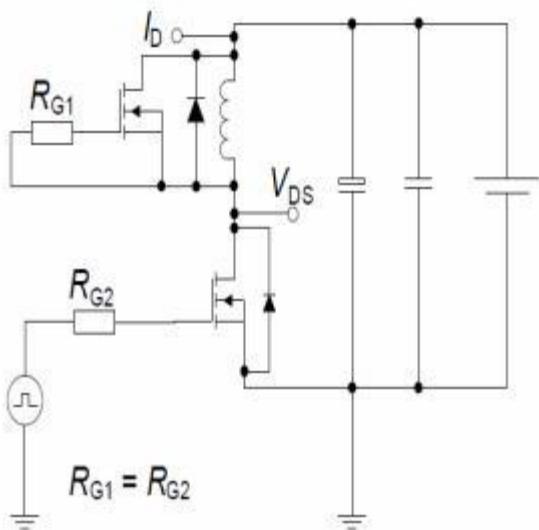
Unclamped inductive waveform



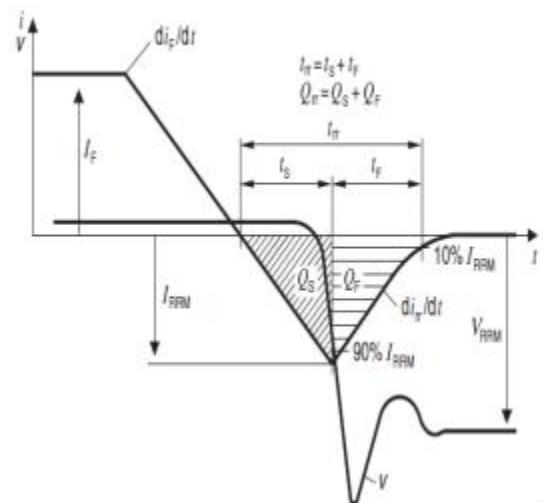
## Test circuits

Test circuit and waveform for diode characteristics

Test circuit for diode characteristics

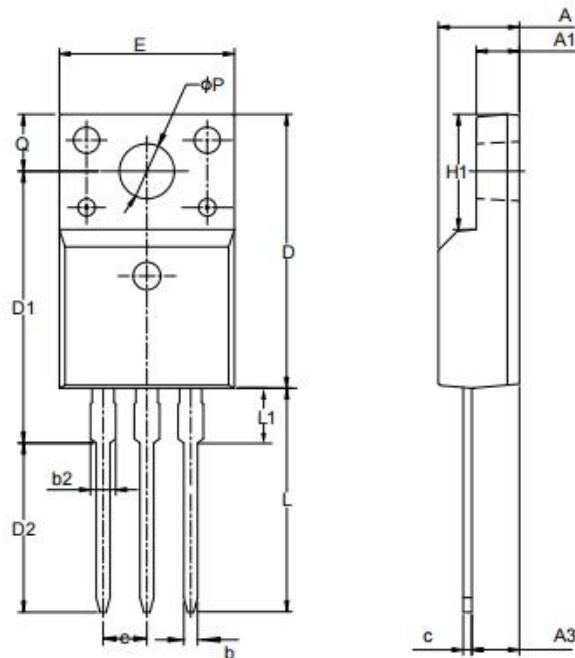


Diode recovery waveform



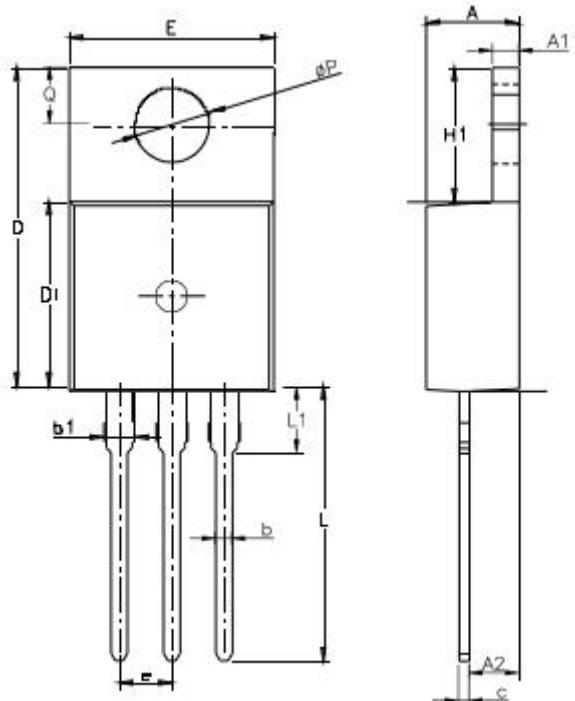
## Package Outline

TO-220 Full PAK



COMMON DIMENSIONS			
Items	Values(mm)		
	MIN	NOM	MAX
A	4.42	4.7	5.02
A1	2.3	2.54	2.8
A3	2.5	2.76	3.1
b	0.7	0.8	0.9
b2	--	--	1.47
c	0.35	0.5	0.65
D	15.25	15.87	16.25
D1	15.3	15.75	16.3
D2	9.3	9.8	10.3
E	9.73	10.16	10.36
e	2.54BSC		
H1	6.4	6.68	7
L	12.48	12.98	13.48
L1	--	--	3.5
øP	3	3.18	3.4
Q	3.05	3.3	3.55

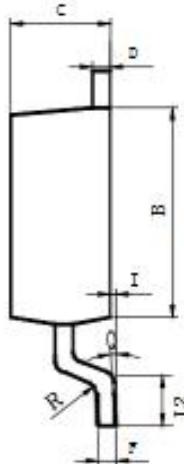
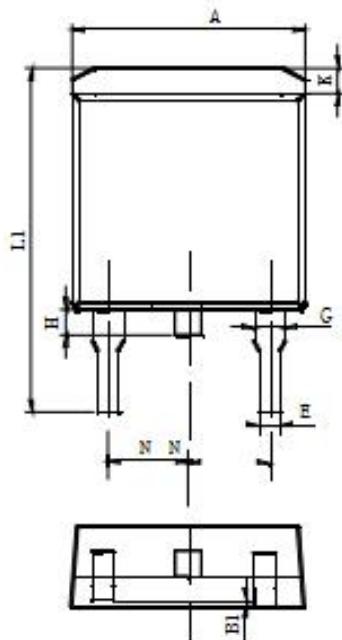
TO-220-3L



COMMON DIMENSIONS			
Items	Values(mm)		
	MIN	NOM	WAX
A	4.3	4.5	4.7
A1	1	1.3	1.5
A2	1.8	2.4	2.8
b	0.6	0.8	1
b1	1	-	1.6
c	0.3	-	0.7
D	15.1	15.7	16.1
D1	8.1	9.2	10
F	9.6	9.9	10.4
e	2.54BSC		
H1	6.1	6.5	7
L	12.6	13.08	13.6
L1			3.95
øP	3.4	3.7	3.9
Q	2.6		3.2

## Package Outline

TO-263-2L



Items	Values(mm)		
	MIN	NOM	MAX
A	9.8	10	10.4
B	8.9	9.6	9.5
B1	0	-	0.1
C	4.4	4.5	4.8
D	1.16	1.4	1.5
E	0.7	0.75	0.95
F	0.3	0.45	0.6
G	1.07	1.38	1.47
H	1.3	-	1.8
K	0.95	1	1.37
L1	14.5	15.2	16.5
L2	1.6	2	2.3
I	0	-	0.2
Q	0°	3°	8°
R	0.4		
N	2.35	2.4	2.7